Unconfirmed Meeting Minutes: Meeting of the IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force

July 14, 2020 Electronic Task Force meeting

Prepared by George Zimmerman, CME Consulting/ADI, Cisco, CommScope, Marvell, SenTekse (Day 1) Prepared by Robert Voss, Panduit/Panduit (Day 2)

IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force meeting convened at 7:00AM PDT, Tuesday, July 14, 2020 by Chad Jones, as acting Chair of the Task Force.

Due to cancellation of the 802 plenary venue, related to COVID-19 pandemic concerns, the meeting was held electronically via WebEx.

Attendance is listed in Appendix A

Administrative Matters

Mr. Jones appointed George Zimmerman as recording secretary for this session. Mr. Jones then handed control of the meeting to David Law, 802.3 Working Group chair.

Mr. Law explained that the Working Group chair appoints the Task Force Chair, and the Task Force would confirm the appointment. Mr. Law then reminded the group that he had announced his intention to appoint Chad Jones Task Force Chair and he then appointed Mr. Jones as the Task Force Chair.

Mr. Jones then left the teleconference and the following motion was made:

<u>Motion #1:</u> Confirm Chad Jones as the IEEE 802.3da 10 Mbps Single Pair Multidrop Segments Enhancement Task Force Chair.

M: Bob Voss S: Peter Jones

MOTION PASSES BY VOICE WITH UNANIMOUS CONSENT

Mr. Jones rejoined the teleconference, and Mr. Law then turned the meeting over to Task Force Chair, Chad Jones.

All presentations referenced in these minutes are located on the July 2020 IEEE P802.3da Task Force website.

This being a teleconference meeting, the Chair asked that participants introduce themselves when speaking, in lieu of a formal roll call. There was no objection.

Mr. Jones displayed the agenda in http://www.ieee802.org/3/da/public/jul20/8023da_agenda_0720.pdf

Motion #2: Move to approve the agenda for the July 2020 meeting (shown in <u>8023da_agenda_0720.pdf</u>).

M: Fred Dawson S: Gergely Huszak Approved by voice without opposition (Procedural > 50%) Motion Passes by voice without objection

The Chair then noted that the minutes from the final Single Pair Multidrop Enhancements Study Group, held on May 18, had been posted for some time, and heard the following motion:

Motion #3: Move to approve the minutes from the May 18 Single Pair Multidrop Enhancements Study Group meeting

M: Bob Voss S: Bernd Horrmeyer Motion passes by voice without objection (Procedural > 50%)

The chair resumed with the agenda deck.

Chair reviewed the goals for the meeting, big ticket items, access to the reflector and website, and ground rules for the meeting.

Attendance, Mr. Jones advised the group that the attendance would be taken from Webex, but that participants needed to sign into IMAT for 802.3 attendance credit. As announced by Mr. Law, attendance at a meeting on 6 unique days of the 802.3 plenary period was required for 802.3 voting rights credit.

Members of the Press, Mr. Jones asked if there were any members of the press present, none responded.

IEEE Patent Policy, Mr.Jones read aloud slides #1 and #2. Mr. Jones then made the call for potentially essential patents at **7:19 AM**, none responded. Mr. Jones then read aloud slides #3 and #4.

At this point, there was a request for clarification on the patent policy regarding patents issued vs. otherwise, and this request was deferred to D. Law. Mr. Law took the question offline.

Mr. Jones resumed review of the agenda deck, including the following items – a review of the participation policy, a review of the IEEE copyright policy, a review of the IEEE policy on dominance, and a review of the IEEE Standards process. There were no questions.

At 7:28 AM, he then completed the review of the agenda document, including that a liaison letter to 802.3 had been received from TIA TR42 and delegated to the 802.3da Task Force to consider a response.

At this time, Mr. Law came back with a response to the question on the patent policy:

The question was whether the call for patents applied to pending patents or only issued patents. Mr. Law referred to FAQ <<u>https://standards.ieee.org/content/dam/ieee-</u><u>standards/standards/web/documents/other/patents.pdf#page=3</u>>. Specifically, item "1 – What is an Essential Patent Claim?" With that clarification, the Chair re-issued the call for patents (7:33AM), and there were no responses.

Presentations and Discussion:

At 7:36AM the Chair moved on to the presentations.

Presentations: - Steps toward baseline text – Kent Lusted, presented by Chad Jones (Cisco systems)

- http://www.ieee802.org/3/da/public/jul20/lusted_3ck_01a_0518.pdf

Liaison Received:

The Chair then moved to the liaison letter forwarded by the 802.3 chair: **TIA TR-42 liaison to IEEE on Base-T1 isolation**

<u>http://www.ieee802.org/3/minutes/mar20/incoming/TR-</u>
<u>42%20liaison%20to%20IEEE%20802.3%20on%20BASET1%20isolation.pdf</u>

The liaison was received in January 2020. There was some discussion of the liaison, which referred to isolation classes and working voltages for a number of single pair applications, most of which are point-to-point.

There was discussion as to what the liaison was asking for, and a decision was made to convene an ad hoc to consider and propose a draft for response to TIA.

The Chair announced an Ad hoc would be held on Friday 7/17 at 8AM PDT.

The Chair then asked the group's consent to jump the agenda to accommodate some presentations.

Presentation: Mixing Segment Recovery/Redundancy Termination, Gergely Huszak (Kone)

The presenter discussed what happens to a mixing segment if there is a break in the cable between nodes and possible approaches to deal with this.

Questions were asked and answered.

Work Items:

The Chair (C. Jones) then moved back to the agenda item for identifying the work items, which had been circulated on the reflector: <u>http://www.ieee802.org/3/SPMD/email/msg00143.html</u> He reviewed a list of potential items and edited online, posting the result as: <u>http://www.ieee802.org/3/da/workitems/index.html</u> - this is intended to be a living list.

The Chair suggested others could add to the list via the reflector.

Presentation: Multidrop Classification, Heath Stewart, Analog Devices

The presenter discussed application of power and querying the link segment for what voltage PD was present. There was discussion of the assumptions of the presenter, and parameters to be discussed - questions came up, among them (not complete):

- Number of voltages to be supported
- Number of nodes to support (relationship to capacitance and inductance at the MDI)
- How are hybrid nodes (nodes that support multiple voltages) supported? (proposed as a separate data point)
- Handling hot inserts (when there isn't an opportunity to do classification)
- Classification as envisioned by the presenter is only during startup of the PSE
- Standby power (turnoff decision) isn't addressed at this time
- Relationship to "active T" presentation

Discussion concluded at 8:57AM

The Chair, noting the time and the meeting was scheduled to recess at 9am, recessed the meeting at 8:59AM.

Presentations would resume on Monday the 20th at 7am PDT.

20 July 2020 Meeting called to order by Mr. Jones (chair) at 903AM CDT

Day 2 attendance is listed in Appendix B

Chair reviewed essential slides with group, reminding TF of detailed review from 14Jul session of meeting, pointing to the slides covering the patent policy, the copyright policy, the IEE Code of Ethics and Conduct, and the IEEE Participation policy.

The Chair called on the members to register their attendance in imat.

At 908am CDT, the chair moved on to presentations

Presentation – George Zimmerman <u>"Enhanced Multidrop with Interoperability" – what do we need?</u> The presenter made the case for, and highlighted some of the issue with, multidrop interoperability. Questions were asked and answered.

At 942am CDT, Peter Jones began **presenting** "<u>LLDP Overview and Use Cases</u>" Use of LLDP as part of our negotiating mechanisms, relating to 802.3da TF Objective 3 Questions were asked and answered.

At 1015am CDT, Chris Diminico began **presenting** "<u>SPE Multidrop Enhancements Mixing Segment</u> <u>Consideration Update</u>"

Parametric link segment model discussion No questions posed to presenter

AT 1036am CDT, the chair shared a work in process response to the **liaison letter** received from TIA TR42. Chair called for discussion of letter. It was pointed out that the letter was addressed to the chair of 802.3cg, which has concluded its work. It was suggested that the letter make note that 802.3cg is complete. The TF Chair will discuss with the WG chair and add this to the letter before presenting in the Thursday closing meeting if needed.

At 1040am CDT, the chair presented "Project Timeline" presentation

Chair asked for input to and discussion of proposed timeline. It was suggested that the timeline wasn't aggressive enough and the group decided to remove on cycle from TF review.

1045am CDT:

Motion #4: Move to adopt proposed timeline as the IEEE P802.3da timeline

M = Peter Jones **S** = George Zimmerman

Motion passes by voice with unanimous consent

Future Meetings

September interim likely to be teleconference, week of 21Sept2020 November plenary will be a teleconference, week of 09Nov2020 January 2021 Interim, week of 18Jan2021 Ad Hoc Meeting series

The chair announced the continuation of the standing Ad Hoc meeting series. Meetings between now and the assumed September teleconference meetings: August 12, August 26, September 29

The chair then appointed two Ad Hoc chairs:

George Zimmerman will chair an ad hoc on channel/noise model, etc. as proposed in his presentation Peter Jones will be 802.3da ad hoc chair Chair called for any other business - none heard

Next meeting is August 12th (ad hoc)

Having exhausted the agenda, the Chair adjourned meeting at 1058am CDT

Appendix A: Attendees at the IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force : July 14, 2020

List of attendees from Webex (**Bold** indicates logged into Webex without IMAT entry):

Anthony New
Ari Kattainen
Arkadiy Peker
bernd horrmeyer
Chad Jones
chris diminico (Guest)
christopher pohl [Beckhoff]
Clark Carty
Cornelia Eitel (Hirschmann Automation)
Dachen Chiou
Dave Hess
David Brandt
David Law
Denis Beaudoin
Doug Oliver [Ford]
Emilio Cuesta (TE Connectivity)
Eric DiBiaso (Guest)
Fred Dawson
Geoff Thompson
George Zimmerman
Gergely Huszak (Kone)
Gideon Intrater (Dialog, Adesto)
Hans Lakner
Haysam Kadry
Heath Stewart
Hideki Goto (Toyota)
Jairo Bustos
James Withey
Jason Potterf
Kae Dube
Kirsten Matheus (BMW)
Mark Dearing
Marty Gubow (Keysight)

Masood Shariff
Matthias Fritsche (HARTING)
Matthias Wendt, Signify
Michal Brychta
Mick McCarthy
Navaneeth Kumar Narayanasamy
Olindo Savi
Paul Vanderlaan (UL)
Peter Jones
rich boyer
Richard Pitwon
Rick Frosch
Rob Aekins
ROBERT GROW
Robert Voss (PANDUIT)
Ryouma Toyoda
Scott Griffiths (Rockwell Automation)
Scott Wade
Shimon Muller
Simon Mark
Sridhar Ramesh
Steffen Graber
steve.sedio@us.tdk.com
Thomas Rettig
Thuyen Dinh
Tim Baggett (Microchip)
Tobias Islinger
Valerie Maguire
Weiqiang
Wojciech Koczwara (Rockwell Automation)
Yan Zhuang
Yong Kim [Axonne]

List of those that logged attendance in imat (Bold indicates logged into IMAT without Webex entry):

Name Baggett, Tim Beaudoin, Denis Affiliation Microchip Technology, Inc. Texas Instruments Incorporated Boyer, Rich Brandt, David Brychta, Michal Bustos Heredia, Jairo Carty, Clark Chiou, Dahcen Cuesta, Emilio Dawson, Fred Dearing, Mark DiBiaso, Eric Diminico, Christopher Dinh, Thuyen Dube, Kathryn Eitel, Cornelia Ferretti, Vincent Fritsche, Matthias Frosch, Richard Goto, Hideki Graber, Steffen Griffiths, Scott Grow, Robert Gubow, Martin Hess, David Horrmeyer, Bernd Huszak, Gergely Islinger, Tobias Jones, Chad Jones, Peter Kadry, Haysam Kim, Yongbum Koczwara, Wojciech Kumada, Taketo Lackner, Hans Law, David Luo, Yuanqiu Maguire, Valerie Mark, Simon Matheus, Kirsten McCarthy, Mick Muller, Shimon New, Anthony Peker, Arkadiy Pohl, Christopher Potterf, Jason Ramesh, Sridhar **Rettig**, Thomas Sedio, Stephen Shariff, Masood

Aptiv Signal and Power Solutions **Rockwell Automation** Analog Devices Inc. Wurth Elektronik Group Cisco Systems, Inc. Dan-Chief Technology **TE Connectivity** Chemours Canada Company Leviton Manufacturing Co. **TE Connectivity** Panduit Corp. **Pulse Electronics UNH-IOL** Hirschmann Automation and Control, Inc. **Corning Incorporated** HARTING Electronics GmbH Phihong USA Inc, **Toyota Motor Corporation** Pepperl+Fuchs AG **Rockwell Automation RMG** Consulting **Keysight Technologies** CORD DATA Phoenix Contact KONE Infineon Technologies AG Cisco Systems, Inc. Cisco Systems, Inc. Ford Motor Company NIO **Rockwell Automation** Yazaki Corporation QoSCom - Quality in Communications - GmbH **Hewlett Packard Enterprise Futurewei Technologies** The Siemon Company Wurth Electronik Group **BMW** Group Analog Devices Inc. Axalume, Inc. Prysmian Cables & Systems Microchip Technology, Inc. **Beckhoff Automation** Cisco Systems, Inc. Maxlinear Inc **Beckhoff Automation TDK** Corporation CommScope, Inc.

Stewart, Heath	Analog Devices Inc.
Thompson, Geoffrey	INDEPENDENT
Toyoda, Ryouma	Yazaki Corporation
Vanderlaan, Paul	UL LLC
Voss, Robert	Panduit Corp.
Wade, Scott	DiiA
Wendt, Matthias	Signify
Withey, James	Fluke Corporation
Xu, Yu	Huawei Technologies Co. Ltd
Zimmerman, George	CME Consulting/ADI, CommScope, Cisco Systems, Marvell, and SenTekse

Appendix B: Attendees at the IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force : July 20, 2020

List of attendees from Webex (**Bold** indicates logged into Webex without IMAT entry):

List of attendees from Webex (bold maleates	
Alex Ingrassia [Canova Tech]	Ichiro Ogura (PETRA)
Alex Lin	Islinger Tobias (IFAG ATV PS PSS TM SPE)
Amrit Gopal (Ford)	James Withey
Anthony New (Prysmian Group)	Jason Potterf
Arkadiy Peker	Jim Theodoras (HG Genuine)
Ayla Chang	John DeAndrea, II-Vi/Finisar
bernd horrmeyer	JOHN S ABBOTT
Bob Voss (PANDUIT)	kenghua
Chad Jones	Kirsten Matheus (BMW)
chris diminico (Guest)	Leon Bruckman (Guest)
Christopher Pohl [Beckhoff Automation]	Mark Bordogna (Intel)
Clark Carty	Mark Dearing LEVITON
Cornelia Eitel (Hirschmann)	Marty Gubow (Keysight)
Dave Hess	Masood Shariff
David D. Brandt	Matthias Wendt, Signify
David Law (HPE)	Michal Brychta (Analog Devices)
Dayin Xu (Guest)	Mick McCarthy - Analog Devices
dokim(hkmc)	Olindo Savi
Douglas Oliver [Ford]	Paul Brooks (Viavi Solutions)
Emilio Cuesta (TE Connectivity)	Paul Vanderlaan (UL)
Eric DiBiaso (Guest)	Peter Jones
Flavio Marques / Furukawa Electric	Qingya She
Fred Dawson	rich boyer
George Zimmerman	Rick Frosch
Gergely Huszak (Kone)	Rob Aekins
Gideon Intrater (Adesto)	Rory Buchanan
Hans Lackner QoSCom GmbH	Scott Griffiths (Rockwell Automation) (Guest)
Hao Ren (Huawei)	Scott Wade (DiiA)
Harry Aller (Innovative Lighting)	Simon Mark (Würth Elektronik)
Haysam Kadry	Steffen Graber (Pepperl+Fuchs SE)
Hideki Goto, Toyota	steve.sedio@us.tdk.com
Hideki Isono (FOC)	Tadashi Takahashi(Nitto Denko Corporation)
Hossein Sedarat	Taiji Kondo, MegaChips

Takayama, Kazuya (Nitto Denko Corp.)
Takeo Masuda
Theo Brillhart (Fluke)
Thomas Rettig
Thuyen Dinh
Tim Baggett (Microchip)
Tobias Islinger, Infineon
Tomohiro Kikuta (Adamant Namiki Precision
Jewel Co., Ltd.)

Valerie Maguire
Wojciech Koczwara (Rockwell Automation)
(Guest)
Xiang He (Huawei)
Xinyuan Wang(Huawei)
YANG YUMENG
Yasuhiro Hyakutake (AD-Na)
Zhigang Gong (O-Net)

List of those that logged attendance in imat (Bold indicates logged into IMAT without Webex entry):

Name Affiliation **Corning Incorporated** Abbott, John Aekins, Rob Legrand Microchip Technology, Inc. Baggett, Tim bordogna, mark Intel Boyer, Rich Aptiv Signal and Power Solutions Brandt, David **Rockwell Automation** Brillhart, Theodore Fluke Corporation Brooks, Paul **Viavi Solutions** Bruckman, Leon HUAWEI Brychta, Michal Analog Devices Inc. Buchanan, Rory **ON Semiconductor** Carty, Clark Cisco Systems, Inc. Chang, Xin Huawei Technologies Co. Ltd Chuang, Keng Hua Hewlett-Packard Development Company, L.P. Cuesta, Emilio **TE Connectivity Chemours Canada Company** Dawson, Fred Deandrea, John **Finisar Corporation** Dearing, Mark Leviton Manufacturing Co. DiBiaso, Eric **TE Connectivity** Diminico, Christopher Panduit Corp. Dinh, Thuyen **Pulse Electronics** Eitel, Cornelia Hirschmann Automation and Control, Inc. Frosch, Richard Phihong USA Inc, Fukuoka, Takashi AutoNetworks Technologies Ltd.; Sumitomo Electric Industries, Ltd. Gong, Zhigang O-Net Communications Ltd. Goto, Hideki **Toyota Motor Corporation** Graber, Steffen Pepperl+Fuchs SE Griffiths, Scott **Rockwell Automation** Gubow, Martin **Keysight Technologies** Gustlin, Mark Cisco Systems, Inc. He, Xiang HUAWEI Hess, David CORD DATA Horner, Rita Synopsys, Inc. **Phoenix Contact** Horrmeyer, Bernd Huszak, Gergely KONE HYAKUTAKE, YASUHIRO Adamant Namiki Precision Jewel Co., Ltd.

Intrater, Gideon **ISHIBE, KAZUHIKO** Islinger, Tobias Isono, Hideki Jones, Chad Jones, Peter Kadry, Haysam Kikuta, Tomohiro Koczwara, Wojciech Kondo, Taiji Lackner, Hans Lim, Jane Lin, Alex Maguire, Valerie Mark, Simon Marques, Flavio Matheus, Kirsten McCarthy, Mick **Muller, Shimon** New, Anthony Nicholl, Gary Ogura, Ichiro Pohl, Christopher Potterf, Jason Ramesh, Sridhar Ren, Hao **Rettig**, Thomas Savi, Olindo Sedarat, Hossein Sedio, Stephen Shariff, Masood She, Qingya Takahashi, Tadashi Takayama, Kazuya Theodoras, James Vanderlaan, Paul Voss, Robert Wade, Scott Wang, Xinyuan Wendt, Matthias Withey, James Xu, Dayin YANG, Yumeng Zhuang, Yan Zimmerman, George **Dialog Semiconductor** Anritsu Company Infineon Technologies AG Fujitsu Optical Components Limited Cisco Systems, Inc. Cisco Systems, Inc. Ford Motor Company Adamant Namiki Precision Jewel Co., Ltd. **Rockwell Automation MegaChips Corporation** QoSCom - Quality in Communications - GmbH Cisco Systems, Inc. MediaTek Inc. The Siemon Company Wurth Electronik Group FURUKAWA ELECTRIC **BMW** Group Analog Devices Inc. Axalume, Inc. Prysmian Cables & Systems Cisco Systems, Inc. PETRA **Beckhoff Automation** Cisco Systems, Inc. Maxlinear Inc HUAWEI **Beckhoff Automation** Hubbell Incorporated Ethernovia **TDK Corporation** CommScope, Inc. **Fujitsu Network Communications** Nitto Denko Corporation Nitto Denko Corporation HG Genuine UL LLC Panduit Corp. DiiA Huawei Technologies Co. Ltd Signify **Fluke Corporation Rockwell Automation** Huawei Technologies Co., Ltd Huawei Technologies Co. Ltd CME Consulting/ADI, CommScope, Cisco Systems, Marvell, and SenTekse